



Title of Change:	Update to FPCN21497Z - Assembly & Test site transfer of SMB products currently manufactured in ON Semiconductor Malaysia facility (SBN) to ON Semiconductor Vietnam (OSV) facility.
Proposed Changed Material First Ship Date:	07 June 2018 (OSV parts available for earlier conversions)
Current Material Last Order Date:	31 March 2018 Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.
Current Material Last Delivery Date:	31 May 2018 The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory.
Product Category:	Active components – Discrete components
Contact information	Contact your local ON Semiconductor Sales Office or <Phuong.Hoang@onsemi.com>
Samples	Contact your local ON Semiconductor Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification.
Sample Availability Date:	Samples Available On Request
PPAP Availability Date:	PPAP Available On Request
Additional Reliability Data	Contact your local ON Semiconductor Sales Office or <cheanching.sim@onsemi.com >.
Type of Notification	This is an update to a Final Product/Process Change Notification (FPCN) sent to customers. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change Category	Type of Change
Process – Assembly	Move of all or part of assembly to a different location/site/subcontractor.
Test Flow	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.
Description and Purpose:	
<p>This Update Notification (UN) is issued to communicate the transfer of Assembly and Test of SMB products from ON Semiconductor Malaysia (SBN) to ON Semiconductor Vietnam (OSV) in order to ensure support for joint growth and alleviate SBN manufacturing capacity constraints.</p> <p>The OSV produced devices will utilize the same BOM, Equipment, and Processes. No change to the SBN affected device list of the original FPCN. No change to the request for qualification of the Assembly & Test processes at the ON Semiconductor Vietnam facility announced in FPCN21497Z utilizing the OSV specific part numbers.</p> <p>The OSV part numbers, identified in FPCN21497Z, are available to early adaptors for immediate SBN demand conversion. You can view a list of those OSV part numbers, cross referenced to the affected SBN part numbers listed in this Update notification, in the attached Excel file.</p> <p>Upon completion of this transfer, SMB demand will be sourced solely from OSV and will no longer be available from SBN. At that time, either the transferring SBN or the current OSV part numbers can be utilized to order these products from OSV.</p>	



<p>Reason / Motivation for Change:</p>	<ul style="list-style-type: none"> • Change benefits for customer(s): <ul style="list-style-type: none"> ○ Unconstrained Automotive Sourcing; Mfg floor space for future expansion ○ Sustained TS16949 Certification with the Same BOM / Equipment / Processes ○ Allow for increased support for Seremban packages that are currently constrained ○ OSV has been audited to VDA6.3 • Risks for delayed conversion: <ul style="list-style-type: none"> ○ No Seremban supply after Dec 31, 2017 ○ Limited ability to support bridge build availability.
<p>Anticipated impact on fit, form, function, reliability, product safety or manufacturability</p>	<p>No anticipated impacts. The device(s) has been qualified and validated based on the same Product Specification. The device(s) has successfully passed the AEC-Q101 qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded.</p>
<p>Sites Affected:</p> <p> <input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : <i>ON Seremban, Malaysia</i> <i>ON Dong Nai Province, Vietnam</i> <input type="checkbox"/> External Foundry/Subcon site(s) </p>	
<p>Marking of Parts/ Traceability of Change:</p>	<p>Products from OSV will carry site code "VN" at the bottom of the package.</p>
<p>Reliability Data Summary:</p> <p>No Changes. Successfully Passed AEC-Q101 Qualification. Please refer to original FPCN</p>	
<p>Electrical Characteristic Summary:</p> <p>No Changes. Electrical characteristics are not impacted. Please refer to original FPCN</p>	
<p>List of Affected Standard Parts:</p>	
<p>Transferring Malaysia (SBN) Part Number</p>	<p>Qualification Vehicle</p>
<p>SURS8110T3G</p>	<p>MURS360BT3G</p>
<p>SURS8120T3G</p>	
<p>SURS8160T3G</p>	
<p>NRVUS230T3G</p>	
<p>NRVUS240T3G</p>	
<p>SURS8220T3G</p>	
<p>SURS8360BT3G</p>	
<p>SURS360DBT3G</p>	
<p>SURHS8160T3G</p>	



Update Notification

Document # : FPCN21497Z1

Issue Date: 07 June 2017

SZ1SMB5915BT3G	P6SMB200AT3G
SZ1SMB5917BT3G	
SZ1SMB5931BT3G	
SZ1SMB5934BT3G	
SZ1SMB5935BT3G	
SZ1SMB5938BT3G	